

ABSTRACT

A wafer treatment apparatus is divided into a working zone (S1) and a loading zone (S2) by a wall (2). A closed wafer cassette (3) has a cassette body 31 having a bottom wall provided with a normally closed valve (5). A vent pipe (51) has one end part
5 projecting from a cassette table (6) disposed in the working zone (S1) and the other end part opening into the loading zone (S2). When the cassette (3) is placed on the cassette table (6), the vent pipe (51) wedges through an incision formed in the valve (5) into the wafer cassette (3) to enable the interior of the
10 cassette (3) to communicate with the loading zone (S2). Consequently, the pressure difference between the interior of the cassette (3) and the loading zone (S2) is reduced to naught.